FAIRCHILD

SEMICONDUCTOR

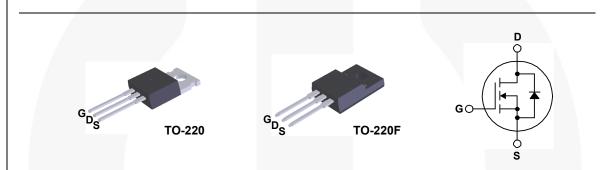
FQP2N60C / FQPF2N60C N-Channel QFET[®] MOSFET 600 V, 2 A, 4.7 Ω

Description

This N-Channel enhancement mode power MOSFET is • 2 A, 600 V, R_{DS(on)} = 4.7 Ω (Max.) @ V_{GS} = 10 V, produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state • Low Gate Charge (Typ. 8.5 nC) resistance, and to provide superior switching performance • Low Crss (Typ. 4.3 pF) and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power • 100% Avalanche Tested factor correction (PFC), and electronic lamp ballasts.

Features

- $I_{D} = 1 A$



Absolute Maximum Ratings T_c = 25°C unless otherwise noted.

Symbol	Parameter	FQP2N60C	FQPF2N60C	Unit	
V _{DSS}	Drain-Source Voltage	6	V		
I _D	Drain Current - Continuous (T _C = 25°C)		2.0	2.0 *	А
	- Continuous (T _C = 100°C)		1.35	1.35 *	А
I _{DM}	Drain Current - Pulsed	8	8 *	А	
V _{GSS}	Gate-Source Voltage	± 30		V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	120		mJ
I _{AR}	Avalanche Current	(Note 1)	2.0		Α
E _{AR}	Repetitive Avalanche Energy	5.4		mJ	
dv/dt	Peak Diode Recovery dv/dt	4.5		V/ns	
P _D	Power Dissipation (T _C = 25°C)		54	23	W
	- Derate above 25°C		0.43	0.18	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150		°C	
т	Maximum Lead Temperature for Soldering,		300		°C
ΤL	1/8" from Case for 5 Seconds				

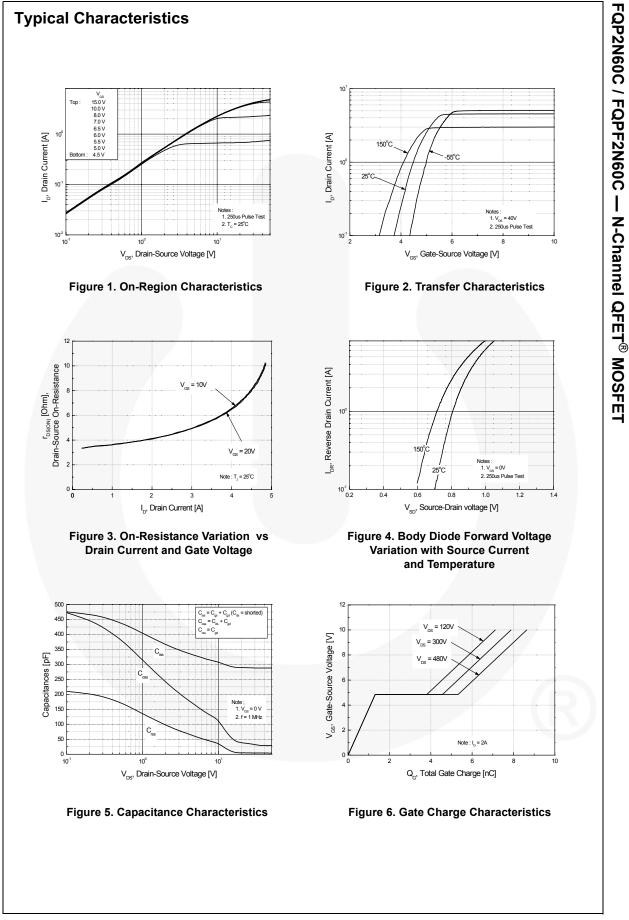
Thermal Characteristics

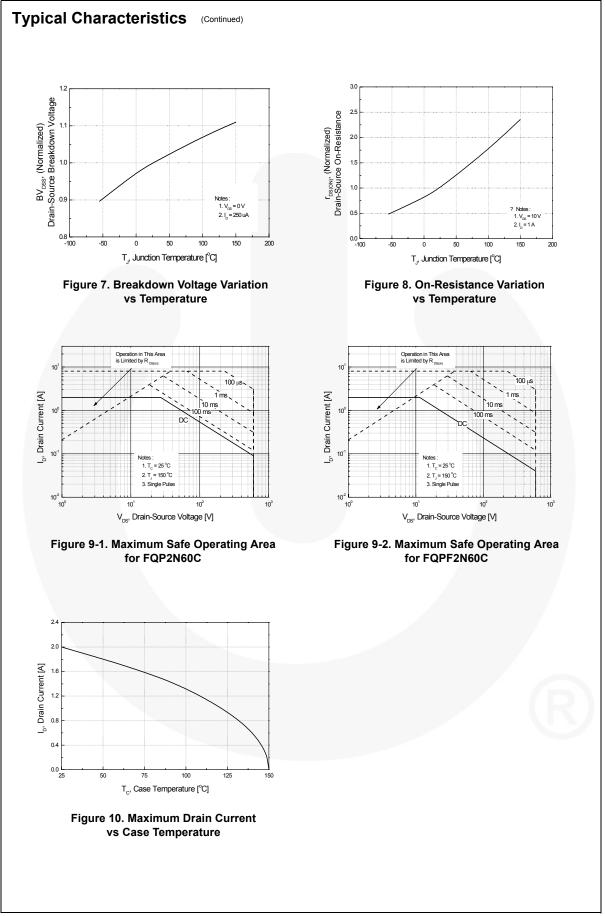
Symbol	Parameter	FQP2N60C	FQPF2N60C	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	2.32	5.5	°C/W	
R _{0CS}	Thermal Resistance, Case-to-Sink Typ, Max.	0.5		°C/W	
R _{θJA}	Thermal Resistance, Junction-to-Ambient, Max.	62.5	62.5	°C/W	

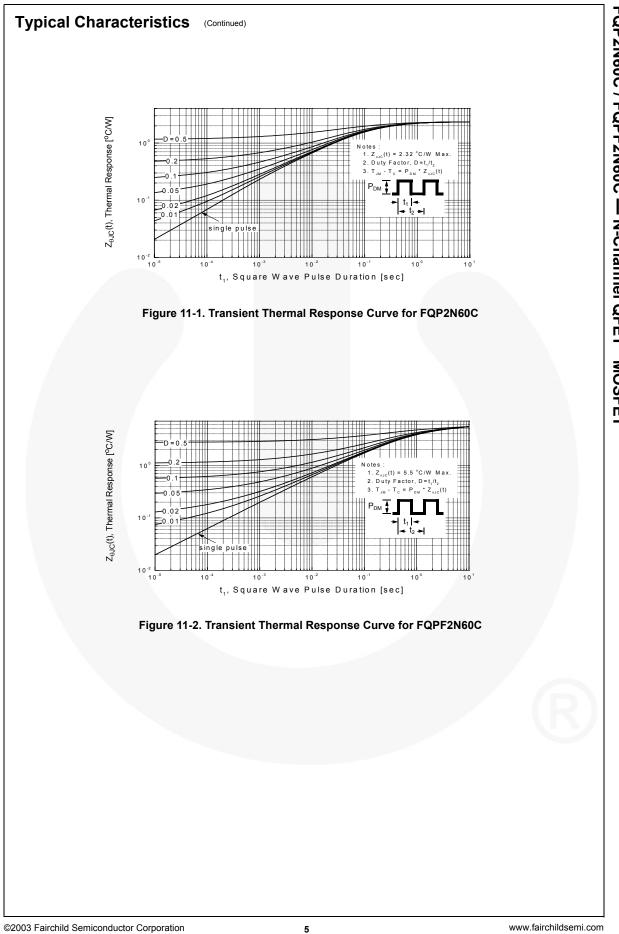
FQP2N60C FQP2N60C TO		Top Mark	Package Packing Method		Reel Size		Tape Width		Quantity	
		TO-	0-220 Tube N/		Ą	N/A		50 units 50 units		
		TO-2	220F Tube N			A	N/A			
Electric	cal Cha	racteristics	T _C = 25°0	C unless othe	rwise noted.					
Symbol	Parameter		Test Conditions		Min.	Тур.	Max.	Unit		
Off Cha	racterist	ics								
BV _{DSS}	Drain-Source Breakdown Voltage		V _{GS} = 0 V, I _D = 250 μA			600			V	
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient		$I_D = 250 \ \mu A$, Referenced to $25^{\circ}C$				0.6		V/°C	
I _{DSS}			V _{DS} = 600 V, V _{GS} = 0 V				1	μA		
Zero Ga		te Voltage Drain Current		V _{DS} = 480 V, T _C = 125°C					10	μA
I _{GSSF}	Gate-Body	y Leakage Current,	Forward	V _{GS} = 30 V, V _{DS} = 0 V					100	nA
I _{GSSR}	Gate-Body	y Leakage Current,	Reverse	V _{GS} = -:	30 V, V _{DS} = 0 V				-100	nA
On Cha	racterist	ics								
V _{GS(th)}		shold Voltage	_	V _{DS} = V	′ _{GS} , I _D = 250 μA		2.0		4.0	V
r _{DS(on)}	Static Drain-Source On-Resistance			$V_{GS} = 10 V, I_D = 1 A$				3.6	4.7	Ω
9 _{FS}		ransconductance	_	V _{DS} = 4	0 V, I _D = 1 A			5.0		S
Dynami	ic Charad	storistics						1		
C _{iss}	ic Charac		_					180	235	pF
C _{oss}	Output Cap		_		5 V, V _{GS} = 0 V,			20	255	pr
C _{rss}	•	rse Transfer Capacitance		f = 1.0 MHz				4.3	5.6	pF
			0					4.0	0.0	P
		acteristics								
t _{d(on)}	Turn-On D		_	V_{DD} = 300 V, I_D = 2 A, R _G = 25 Ω (Note 4)				9	28	ns
t _r	Turn-On F						25	60	ns	
t _{d(off)}	Turn-Off D Turn-Off F	,					24	58	ns	
t _f				. ,				28	66 12	ns
Q _g	Total Gate	ů.			80 V, I _D = 2 A,			8.5 1.3		nC nC
Q _{gs}	Gate-Sour	rce Charge		V _{GS} = 10 V (Note 4)			4.1		nC	
Q _{gd}	Gale-Dial	in ondige		1		() .,		7.1		no
Drain-S	ource Di	ode Character	istics a	nd Maxi	mum Ratings					
I _S	Maximum Continuous Drain-Source Die			ode Forward Current					2	А
I _{SM}	Maximum Pulsed Drain-Source Diode I			Forward Current					8	А
V _{SD}	Drain-Sou	rce Diode Forward	Voltage	V _{GS} = 0 V, I _S = 2 A					1.4	V
t _{rr}	Reverse F	Recovery Time		V _{GS} = 0	V, I _S = 2 A,			230		ns
Q _{rr}	Reverse Recovery Charge		dI _F / dt = 100 A/µs				1.0		μC	

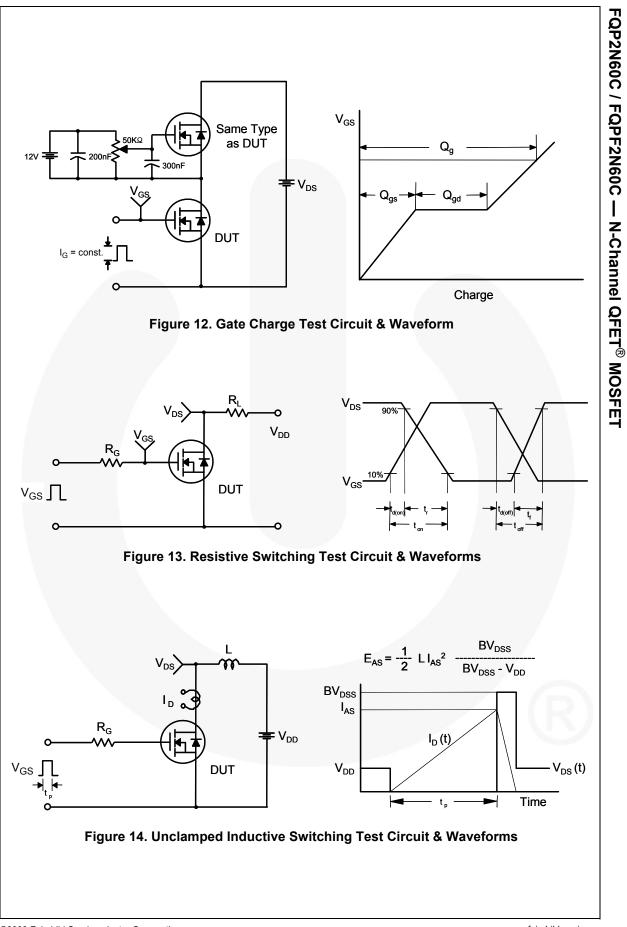
Notes: 1. Repetitive rating : pulse-width limited by maximum junction temperature. 2. L = 56 mH, I_{AS} = 2 A, V_{DD} = 50 V, R_G = 25 Ω , starting T_J = 25°C. 3. I_{SD} ≤ 2 A, di/dt ≤ 200 A/µs , V_{DD} ≤ BV_{DSS}, starting T_J = 25°C. 4. Essentially independent of operating temperature.

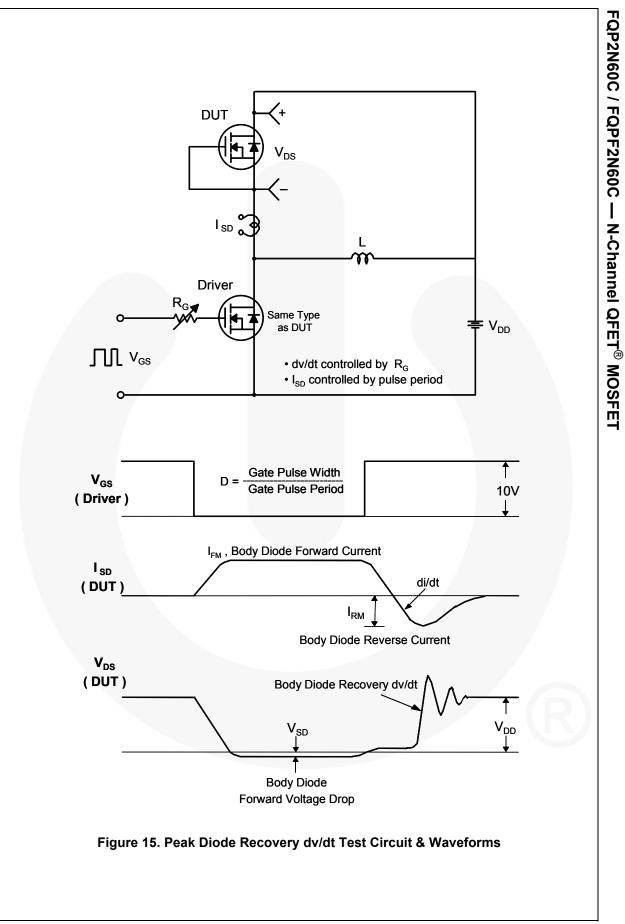
FQP2N60C / FQPF2N60C — N-Channel QFET® MOSFET

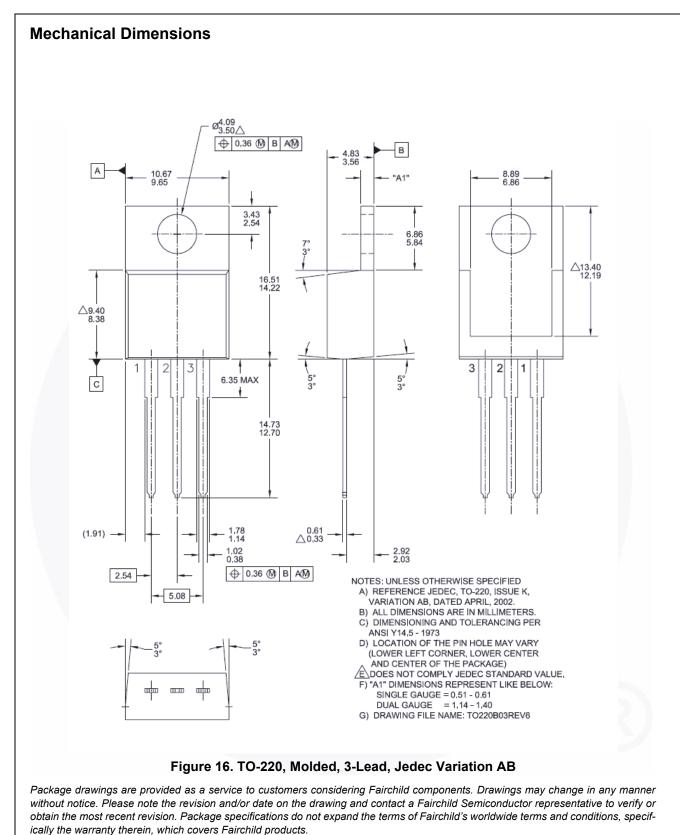






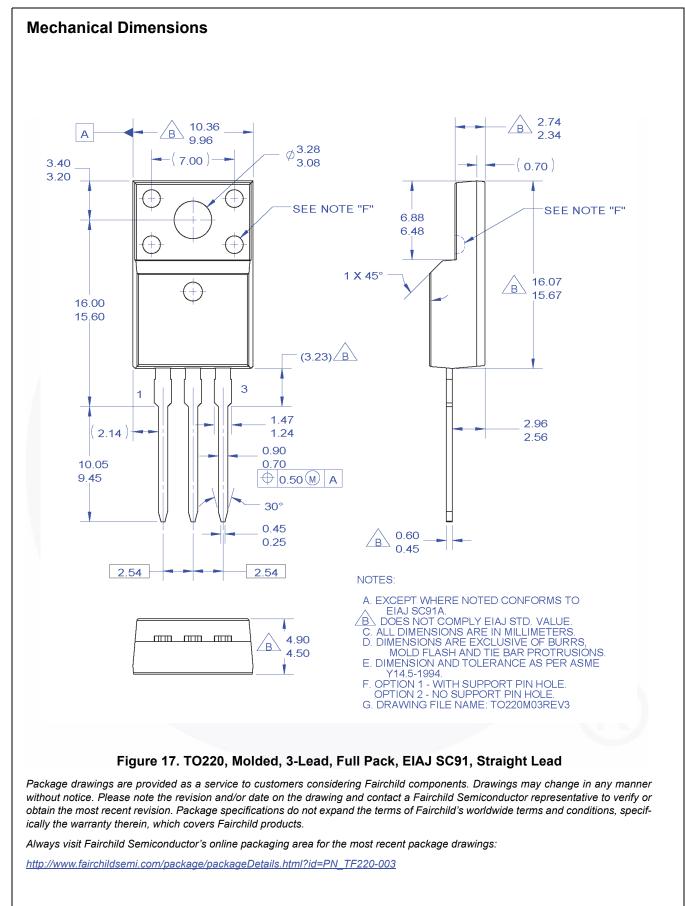






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